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PATENT APPLICATION  
Attorney's Do. No. 9019-33

JCS72 U.S. PTD  
10/016578  
11/01/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re divisional application of:  
JAMES D. PARSONS and B. LEO KWAK

Serial No.:

Group Art Unit:

Filed:

Examiner:

For: ADHESION AND/OR ENCAPSULATION OF SILICON CARBIDE-  
BASED SEMICONDUCTOR DEVICES ON CERAMIC SUBSTRATES

Assistant Commissioner for Patents  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

This application is a divisional of copending U.S. Patent Application Serial No. 09/351,106, filed July 6, 1999, now U.S. Patent No. 6,319,757, to issue November 20, 2001, which claims priority from U.S. Provisional Application Serial No. 60/092,039, filed July 8, 1998. It includes the same disclosure as U.S. patent application Serial No. 09/351,106

It is understood that the listed references will be considered in the examination of the application and that no separate copies of the same prior art are required to be provided since they were previously cited or transmitted in the foregoing prior application. 37 CFR Section 1.98(d). Form(s) PTO 1449 is enclosed listing references cited by the Examining Attorney and submitted by applicant in the prior applications.



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PATENT TRADEMARK OFFICE

Respectfully submitted,

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Form PTO-1449 (modified)  
INFORMATION DISCLOSURE CITATION

Atty. Docket No.  
9109-33

Serial No.

Applicant:  
JAMES D. PARSONS and B. LEO KWAK

Filing Date

Group  
2825

### U.S. Patent Documents

Examiner Initial	Document Number	Date	Name	Class	Subclass
	4,581,279	04/1986	Sugishita et al.	428	209
	4,651,192	03/1987	Matsushita et al.	357	74
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### Non-Patent Documents

#### Other Documents (including Author, Title, Source, Date, Pertinent Pages)

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Bhattacharya, P. K., "Bonding of SiC slabs for electro-mechanical heat-sinks in advanced packaging applications, Int. J. Electronics Vol. 73, No. 1, pp. 71-82, 1992.

Examiner

Date Considered

\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

#2/103  
Biding  
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10872 U.S. PTD  
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Savrun, E. and Toy, C., "An Aluminum Nitride Package for 600°C and Beyond," Proc. IEEE, 1998, 0-7803-4540-1/98, pages 265-268,

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